SCBS251F - JUNE 1992 - REVISED MAY 1997

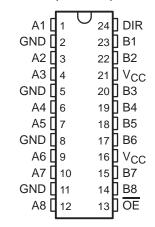
- State-of-the-Art *EPIC-IIB™* BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- **High-Impedance State During Power Up** and Power Down
- **Designed to Facilitate Incident-Wave** Switching for Line Impedances of 25 Ω or
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Bus Hold on Data Inputs Eliminates the **Need for External Pullup/Pulldown** Resistors
- **Package Options Include Plastic** Small-Outline (DW) Package, Ceramic Chip Carriers (FK), and Standard Plastic (NT) and Ceramic (JT) DIPs

description

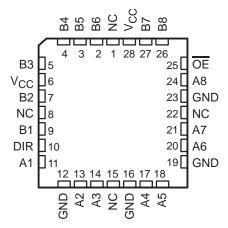
The 'ABTH25245 are 25-Ω octal bus transceivers designed for asynchronous communication between data buses. They improve both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented transceivers.

These devices allow noninverted data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (OE) input can disable the device so that both buses are effectively isolated. When OE is low, the device is active.

SN54ABTH25245 . . . JT PACKAGE SN74ABTH25245...DW OR NT PACKAGE (TOP VIEW)



SN54ABTH25245 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

These transceivers are capable of sinking 188 mA of I_{OL} current, which facilitates switching 25- Ω transmission lines on the incident wave. The distributed V_{CC} and GND pins minimize switching noise for more-reliable system operation.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.



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EPIC-IIB is a trademark of Texas Instruments Incorporated



SN54ABTH25245, SN74ABTH25245 25- Ω OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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description (continued)

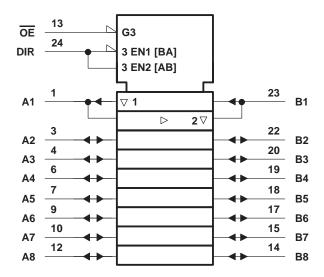
When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABTH25245 is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ABTH25245 is characterized for operation from -40° C to 85° C.

FUNCTION TABLE

INP	UTS	OPERATION
OE	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	Χ	Isolation

logic symbol†

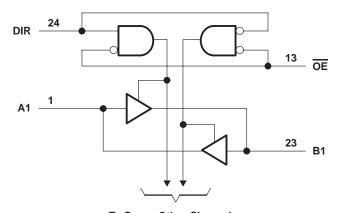


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DW, JT, and NT packages.



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logic diagram (positive logic)



To Seven Other Channels

Pin numbers shown are for the DW, JT, and NT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the disabled or power-off state, VO –	-0.5 V to 5.5 V
Voltage range applied to any output in the high state, VO	-0.5 V to V _{CC}
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Current into any output in the low state, IO: SN74ABTH25245 (A port)	376 mA
SN74ABTH25245 (B port)	128 mA
Package thermal impedance, θ _{JA} (see Note 2): DW package	81°C/W
NT package	67°C/W
Storage temperature range, T _{stq} 6	35°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

SN54ABTH25245, SN74ABTH25245 25- Ω OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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recommended operating conditions (see Note 3)

				SN54ABT	H25245	SN74ABTI	H25245	UNIT
				MIN	MAX	MIN	MAX	UNII
Vcc	Supply voltage			4.5	5.5	4.5	5.5	V
VIH	High-level input voltage			2		2		V
V _{IL}	Low-level input voltage				0.8		8.0	V
VI	Input voltage			0	Vcc	0	Vcc	V
lıK	Input clamp current	-18			-18	mA		
lou	High lovel output ourrent		A port	á	-80		-80	mA
ЮН	High-level output current		B port	5	-32		-32	IIIA
lo	Low-level output current		A port	30	188		188	mA
lOL	Low-level output current		B port	80	64		64	IIIA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	Control inputs	Q	4		4	ns/V
ΔυΔν	input transition rise of fail rate	Outputs enabled	A or B ports		10		10	115/ V
Δt/ΔV _{CC}	Power-up ramp rate			200		200		μs/V
TA	Operating free-air temperature		·	-55	125	-40	85	°C

NOTE 3: Unused control pins must be held high or low to prevent them from floating.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST 64	ONDITIONS	SN54	4ABTH2	5245	SN74	ABTH25	5245	UNIT
PAR	RAMETER	l lesi Co	ONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNII
VIK		V _{CC} = 4.5 V,	I _I = -18 mA			-1.2			-1.2	V
	A port	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.7			2.7			
	A port	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -80 \text{ mA}$	2.4			2.4			
Vон		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$	2.5			2.5			V
	B port	$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$	3			3			
		$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -32 \text{ mA}$	2*			2			
	A port	V _{CC} = 4.5 V	$I_{OL} = 94 \text{ mA}$			0.55			0.55	
V_{OL}	Aport	VCC = 4.5 V	I _{OL} = 188 mA			0.7			0.7	V
	B port	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 64 \text{ mA}$			0.55*			0.55	
V_{hys}	_				100			100		mV
1.	Control inputs	$V_{CC} = 0 \text{ to } 5.5 \text{ V},$	$V_I = V_{CC}$ or GND			±1			±1	μА
ΙΙ	A or B ports	$V_{CC} = 2.1 \text{ V to } 5.5 \text{ V},$	$V_I = V_{CC}$ or GND			±20			±20	μΛ
11/15 = 1 = 1	A or B ports	V _{CC} = 4.5 V	V _I = 0.8 V	100	77		100			μА
l(hold)	A or B ports	VCC = 4.5 V	V _I = 2 V	-100	7		-100			μΛ
lozpu‡		$V_{CC} = 0$ to 2.1 V, $V_{O} = 0$	$0.5 \text{ V to } 2.7 \text{ V}, \overline{\text{OE}} = X$	4	3	±50			±50	μΑ
lozpD [‡]		$V_{CC} = 2.1 \text{ V to } 0, V_{O} =$	0.5 V to 2.7 V, OE = X	0)	±50			±50	μΑ
l _{off}		$V_{CC} = 0$,	V _I or V _O ≤ 4.5 V	Q		±100			±100	μΑ
ICEX		V _{CC} = 5.5 V,	V _O = 5.5 V			50			50	μΑ
ΙΟ§	B port	V _{CC} = 5.5 V,	V _O = 2.5 V	-50		-210	-50		-210	mA
		V _{CC} = 5.5 V,	Outputs high			500			500	μΑ
ICC		Outputs open,	Outputs low			20			20	mA
		$V_I = V_{CC}$ or GND	Outputs disabled			500			500	μΑ
ΔICC¶		$V_{CC} = 5.5 \text{ V}$, One input Other inputs at V_{CC} or 0				1			1	mA
Ci	Control inputs	V _{CC} = 5 V,	V _I = V _{CC} or GND		4			4		pF
C _{io}	A or B ports	V _{CC} = 5 V,	$V_O = V_{CC}$ or GND		11.5			11.5		pF

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[‡] This parameter is characterized, but not production tested.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[¶] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

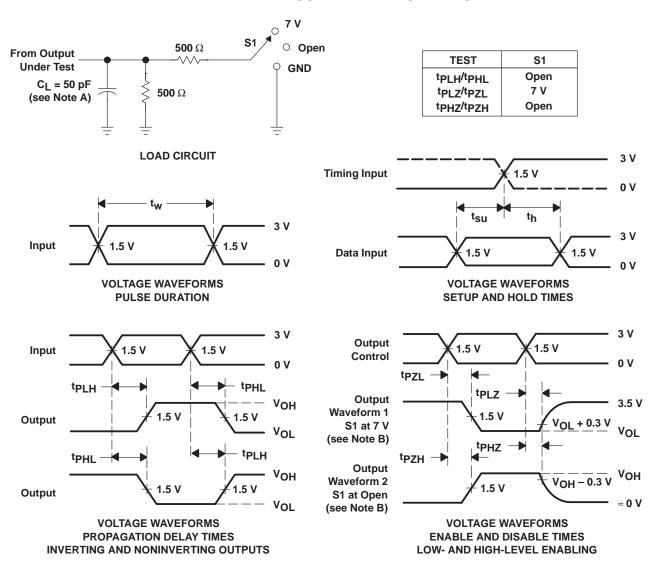
SN54ABTH25245, SN74ABTH25245 25- Ω OCTAL BUS TRANSCEIVERS WITH 3-STATE OUTPUTS

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABTH25245	SN74ABTH25245		UNIT
	(INFOT)	(0011-01)	MIN	TYP	MAX	MIN MAX	MIN	MAX	
tPLH	A or B	P.or A	1	2.3	3.5	1 🔊	1	3.9	no
t _{PHL}	AOIB	B or A	1	2.4	3.5	1 &	1	4.3	ns
^t PZH		A or B	1.5	3.7	5.4	1.5	1.5	6.5	
tPZL	ŌĒ	AUIB	1.4	4	5.8	1.4	1.4	6.8	ns
t _{PHZ}	ŌĒ	A or D	2	4.3	6.1	0 2	2	7.2	
t _{PLZ}	OE .	A or B	2	3.9	5.8	2 2	2	6.4	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \,\Omega$, $t_f \leq$ 2.5 ns. $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN74ABTH25245DW	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH25245
SN74ABTH25245DW.B	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH25245
SN74ABTH25245DWR	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH25245
SN74ABTH25245DWR.B	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH25245
SN74ABTH25245DWRG4	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH25245
SN74ABTH25245DWRG4.B	Active	Production	SOIC (DW) 24	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABTH25245

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.



PACKAGE OPTION ADDENDUM

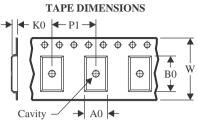
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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

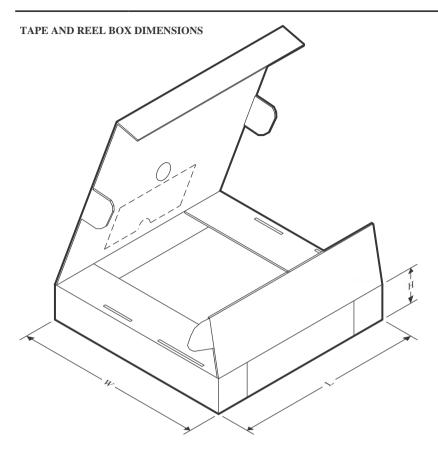


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABTH25245DWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74ABTH25245DWRG4	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

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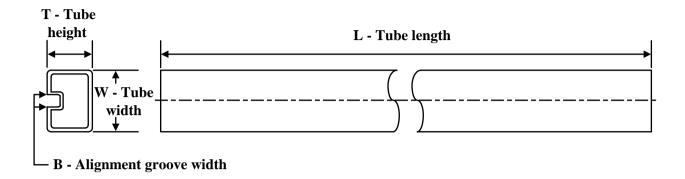
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABTH25245DWR	SOIC	DW	24	2000	350.0	350.0	43.0
SN74ABTH25245DWRG4	SOIC	DW	24	2000	350.0	350.0	43.0

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TUBE

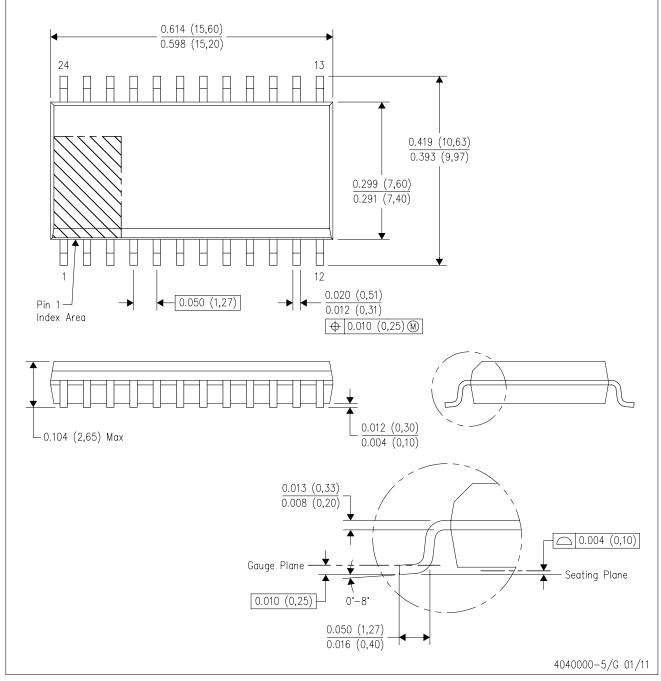


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABTH25245DW	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN74ABTH25245DW.B	DW	SOIC	24	25	506.98	12.7	4826	6.6

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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